




Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STL76DN4LF7AG	BSY6*OL42A82	A	SH1A	2017-07-17
	Amount	UoM	Unit type	ST ECOPACK Grade
	100.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	6, 5, 1	8	pin	
Comment	Package: PowerFLAT 5x6 double island WF			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-12th January 2017				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BSY6*OL42A82					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Dies	Other inorganic materials	0.916	mg	supplier	die	Silicon (Si)	7440-21-3		0.842	mg	919214	8420
				supplier	metallization	Aluminium (Al)	7429-90-5		0.031	mg	33843	310
				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.004	mg	4366	40
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.008	mg	8734	80
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	2183	20
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.021	mg	22926	210
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.008	mg	8734	80
Leadframe	Copper & its alloys	44.932	mg	supplier	alloy	Copper (Cu)	7440-50-8		42.813	mg	952840	428130
				supplier	alloy	Iron (Fe)	7439-89-6		1.007	mg	22412	10070
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.061	mg	1358	610
				supplier	alloy	Zinc (Zn)	7440-66-6		0.053	mg	1179	530
				supplier	metallization	Silver (Ag)	7440-22-4		0.998	mg	22211	9980
Soft solder	Solder	1.697	mg	JIG-R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	1.621	mg	955215	16210
				supplier	solder	Silver (Ag)	7440-22-4		0.042	mg	24750	420
				supplier	solder	Tin (Sn)	7440-31-5		0.034	mg	20035	340
Bonding wire & Clip	Precious metals	7.978		supplier	wire	Gold (Au)	7440-57-5		0.173	mg	21685	1730
				supplier	clip	Copper (Cu)	7440-50-8		7.805	mg	978315	78050
Encapsulation	Other Organic Materials	44.321	mg	supplier	mold compound	Silica, vitreous	60676-86-0		34.793	mg	785023	347930
				supplier	mold compound	epoxy resin	25068-38-6		5.761	mg	129984	57610
				supplier	mold compound	phenol resin	9003-35-4		2.659	mg	59994	26590
				supplier	mold compound	metal hydroxide	21645-51-2		0.886	mg	19991	8860
				supplier	mold compound	Carbon black	1333-86-4		0.222	mg	5008	2220
Connections coating	Solder	0.156	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.156	mg	1000000	1560